GENERAL DESCRIPTION



The ICS87008I is a low skew, 1:8 LVCMOS/LVTTL Clock Generator and is a member of the HiPerClockS™ family of High Performance Clock Solutions. The device has 2 banks of 4 outputs and each bank can be independently selected for

 $\div 1$ or $\div 2$ frequency operation. Each bank also has its own power supply pins so that the banks can operate at the following different voltage levels: 3.3V, 2.5V, and 1.8V. The low impedance LVCMOS/LVTTL outputs are designed to drive 50Ω series or parallel terminated transmission lines.

The divide select inputs, DIV_SELA and DIV_SELB, control the output frequency of each bank. The output banks can be independently selected for $\div 1$ or $\div 2$ operation. The bank enable inputs, CLK_ENA and CLK_ENB, support enabling and disabling each bank of outputs individually. The CLK_ENA and CLK_ENB circuitry has a synchronizer to prevent runt pulses when enabling or disabling the clock outputs. The master reset input, nMR/OE, resets the $\div 1/\div 2$ flip flops and also controls the active and high impedance states of all outputs. This pin has an internal pull-up resistor and is normally used only for test purposes or in systems which use low power modes.

The ICS87008I is characterized to operate with the core at 3.3V or 2.5V and the banks at 3.3V, 2.5V, or 1.8V. Guaranteed bank, output, and part-to-part skew characteristics make the 87008I ideal for those clock applications demanding well-defined performance and repeatability.

FEATURES

- 8 LVCMOS/LVTTL outputs (2 banks of 4 outputs)
- Selectable differential CLK1, nCLK1 or LVCMOS clock input
- CLK1, nCLK1 pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- · CLK0 supports the following input types: LVCMOS, LVTTL
- Maximum output frequency: 250MHz
- Independent bank control for ÷1 or ÷2 operation
- · Glitchless, asynchronous clock enable/disable
- Output skew: 105ps (maximum) @ 3.3V core/3.3V output
- Bank skew: 70ps (maximum) @ 3.3V core/3.3V output
- 3.3V or 2.5V core/3.3V, 2.5V, or 1.8V output operating supply
- -40°C to 85°C ambient operating temperature

BLOCK DIAGRAM

PIN ASSIGNMENT

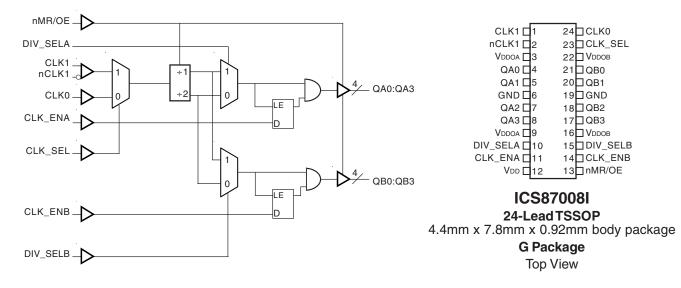


TABLE 1. PIN DESCRIPTIONS

Number	Name	Т	уре	Description
1	CLK1	Input	Pulldown	Non-inverting differential clock input.
2	nCLK1	Input	Pullup/ Pulldown	Inverting differential clock input. V _{DD} /2 default when left floating.
3, 9	$V_{\scriptscriptstyle DDOA}$	Power		Output Bank A supply pins.
4, 5, 7, 8	QA0, QA1, QA2, QA3	Output		Bank A outputs. LVCMOS / LVTTL interface levels.
6, 19	GND	Power		Supply ground.
10	DIV_SELA	Input	Pullup	Controls frequency division for Bank A outputs. LVCMOS / LVTTL interface levels.
11	CLK_ENA	Input	Pullup	Output enable for Bank A outputs. Active HIGH. If pin is LOW, outputs drive low. LVCMOS / LVTTL interface levels.
12	$V_{_{\mathrm{DD}}}$	Power		Core supply pin.
13	nMR/OE	Input	Pullup	Master reset. When LOW, resets the ÷1/÷2 flip flops and sets the outputs to high impedance. LVCMOS / LVTTL interface levels.
14	CLK_ENB	Input	Pullup	Output enable for Bank B outputs. Active HIGH. If pin is LOW, outputs drive low. LVCMOS / LVTTL interface levels.
15	DIV_SELB	Input	Pullup	Controls frequency division for Bank B outputs LVCMOS / LVTTL interface levels
16, 22	V _{DDOB}	Power		Output Bank B supply pins.
17, 18, 20, 21	QB3, QB2, QB1, QB0	Output		Bank C outputs. LVCMOS / LVTTL interface levels.
23	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK1, nCLK1 inputs. When LOW, selects CLK0 input. LVCMOS / LVTTL interface levels.
24	CLK0	Input	Pulldown	LVCMOS / LVTTL clock input.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		ΚΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		ΚΩ
		V_{DD} , $V_{DDOx} = 3.465V$; NOTE 1			18	pF
		V_{DD} , $V_{DDOx} = 2.625V$; NOTE 1			20	pF
C _{PD}	Power Dissipation Capacitance (per output)	$V_{DD} = 3.465, V_{DDOx} = 2.625V; NOTE 1$			20	pF
	Capacitance (per output)	$V_{DD} = 3.465, V_{DDOx} = 1.89V; NOTE 1$			30	pF
		V _{DD} = 2.625, V _{DDOx} = 1.89V; NOTE 1			20	pF
R _{out}	Output Impedance			7		Ω

NOTE 1: V_{DDOx} denotes V_{DDOA} and V_{DDOB} .

TABLE 3. FUNCTION TABLE

	Inputs	Outputs		
nMR/OE	CLK_ENx	DIV_SELx	Bank X	Qx Frequency
0	Х	Х	Hi Z	N/A
1	1	0	Active	fIN/2
1	1	1	Active	fIN
1	0	Х	Low	N/A

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD} 4.6V

Inputs, V_{I} -0.5V to V_{DD} + 0.5 V

Outputs, V_O -0.5V to V_{DDO} + 0.5V

Package Thermal Impedance, $\theta_{IA} = 70^{\circ}\text{C/W} (0 \text{ lfpm})$

Storage Temperature, T_{STG} -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics, $V_{DD} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_A = -40$ °C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V	Cara Cupply Valtage		3.135	3.3	3.465	V
V _{DD}	Core Supply Voltage		2.375	2.5	2.625	V
			3.135	3.3	3.465	V
V _{DDOx}	Output Supply Voltage; NOTE 1		2.375	2.5	2.625	V
			1.71	1.8	1.89	V
I _{DD}	Power Supply Current				54	mA
I _{DDOx}	Output Supply Current; NOTE 2				6.5	mA

NOTE 1: V_{DDOx} denotes V_{DDOA} and V_{DDOB} . NOTE 2: I_{DDOx} denotes I_{DDOA} and I_{DDOB} .

$\textbf{Table 4B. LVCMOS/LVTTL DC Characteristics, V}_{DD} = 3.3 V \pm 5\% \text{ or } 2.5 V \pm 5\%, TA = -40 ^{\circ}\text{C to } 85 ^{\circ}\text{C}$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V _{IH}	Input High Voltage	DIV_SELA, DIV_SELB, CLK_ENA, CLK_ENB, nMR/OE, CLK_SEL		2		V _{DD} + 0.3	V
		CLK0		2		V _{DD} + 0.3	V
V _{IL}	Input Low Voltage	DIV_SELA, DIV_SELB, CLK_ENA, CLK_ENB, nMR/OE, CLK_SEL		-0.3		0.8	V
		CLK0		-0.3		1.3	V
I _{IH}	Input	DIV_SELA, DIV_SELB, CLK_ENA, CLK_ENB, nMR/OE	$V_{DD} = V_{IN} = 3.465V,$ $V_{DD} = V_{IN} = 2.625V$			5	μΑ
ТН	High Current	CLK0, CLK_SEL	$V_{DD} = V_{IN} = 3.465V,$ $V_{DD} = V_{IN} = 2.625V$			150	μΑ
I _{IL}	Input	DIV_SELA, DIV_SELB, CLK_ENA, CLK_ENB, nMR/OE	$V_{DD} = 3.465V, V_{IN} = 0V$ $V_{DD} = 2.625V, V_{IN} = 0V$	-150			μΑ
	Low Current	CLK0, CLK_SEL	$V_{DD} = 3.465V, V_{IN} = 0V$ $V_{DD} = 2.625V, V_{IN} = 0V$	-5			μΑ
			$V_{DDOx} = 3.3V \pm 5\%; NOTE 2$	2.6			V
V _{OH}	Output High V	oltage; NOTE 1	$V_{DDOx} = 2.5V \pm 5\%; NOTE 2$	1.8			V
			$V_{DDOx} = 1.8V \pm 5\%; NOTE 2$	1.5			٧
			$V_{DDOx} = 3.3V \pm 5\%; NOTE 2$			0.5	V
V _{OL}	Output Low Voltage; NOTE 1		$V_{DDOx} = 2.5V \pm 5\%; NOTE 2$			0.5	V
			$V_{DDOx} = 1.8V \pm 5\%; NOTE 2$			0.4	V
I _{OZL}	Output Tristate	e Current Low		-5			μΑ
I _{OZH}	Output Tristate	e Current High				5	μΑ

NOTE 1: Outputs terminated with 50Ω to $V_{DDOX}/2$. See Parameter Measurement Information, Output Load Test Circuits. NOTE 2: V_{DDOX} denotes V_{DDOA} , and V_{DDOB} .

Table 4C. Differential DC Characteristics, V_{DD} = V_{DD} = 3.3V \pm 5\% or 2.5V \pm 5\%, Ta = -40^{\circ}C to 85^{\circ}C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	land High Company	nCLK1	$V_{IN} = V_{DD} = 3.465V,$ $V_{IN} = V_{DD} = 2.625V$			5	μΑ
I IIH	Input High Current	CLK1	$V_{IN} = V_{DD} = 3.465V,$ $V_{IN} = V_{DD} = 2.625V$			150	μΑ
	Input Low Current	nCLK1	$V_{IN} = 0V, V_{DD} = 3.465V,$ $V_{IN} = 0V, V_{DD} = 2.625V$	-150			μΑ
I IIL	Input Low Current	CLK1	$V_{IN} = 0V, V_{DD} = 3.465V,$ $V_{IN} = 0V, V_{DD} = 2.625V$	-5			μΑ
V _{PP}	Peak-to-Peak Input	Voltage		0.15		1.3	V
V _{CMR}	Common Mode Inpo NOTE 1, 2	ut Voltage;		GND + 0.5		V _{DD} - 0.85	٧

NOTE 1: For single ended applications, the maximum input voltage for CLK1, nCLK1 is V_{pp} + 0.3V.

NOTE 2: Common mode voltage is defined as $V_{\rm HI}$.

Table 5A. AC Characteristics, $V_{DD} = V_{DDOx} = 3.3V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency					250	MHz
	Propagation Delay,	CLK0; NOTE 1A		1.9	3.5	5.1	ns
tp _{LH}	Low to High	CLK1, nCLK1; NOTE 1B		3.0	3.7	4.5	ns
tsk(b)	Bank Skew; NOTE 2, 6					70	ps
tsk(o)	Output Skew; NOTE	3, 6				105	ps
tsk(pp)	Part-to-Part Skew; N	IOTE 4, 6				650	ps
t _R / t _F	Output Rise/Fall Tim	пе	20% to 80%	300		1100	ps
odc	Output Duty Cycle		f ≤ 133MHz	45		55	%
t _{EN}	Output Enable Time; NOTE 5					10	ns
t _{DIS}	Output Disable Time	e; NOTE 5				10	ns

All parameters measured at 250MHz using CLK1, nCLK1 unless noted otherwise.

NOTE 1A: Measured from the $V_{DD}/2$ of the input to $V_{DDOX}/2$ of the output. NOTE 1B: Measured from the differential input crossing point to $V_{DDOX}/2$ of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at $V_{DDOX}/2$.

NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at V_DOOX/2.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

Table 5B. AC Characteristics, $V_{DD} = V_{DDOx} = 2.5V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency					250	MHz
	Propagation Delay	CLK0; NOTE 1A		2.0	3.8	5.5	ns
tp _{LH} Propagation Delay, Low to High	CLK1, nCLK1; NOTE 1B		3	4	5	ns	
tsk(b)	Bank Skew; NOTE 2, 6					35	ps
tsk(o)	Output Skew; NOTE	3, 6				130	ps
tsk(pp)	Part-to-Part Skew; N	NOTE 4, 6				1	ns
t _R / t _F	Output Rise/Fall Tim	ne	20% to 80%	300		1000	ps
odc	Output Duty Cycle		f ≤ 125MHz	45		55	%
t _{EN}	Output Enable Time; NOTE 5					10	ns
t _{DIS}	Output Disable Time	e; NOTE 5				10	ns

All parameters measured at 250MHz using CLK1, nCLK1 unless noted otherwise.

NOTE 1A: Measured from the $\rm V_{DD}\!/2$ of the input to $\rm V_{DDOX}\!/2$ of the output.

NOTE 1B: Measured from the differential input crossing point to $V_{\tiny DDOX}/2$ of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at V_{DDOX}/2.

NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with

equal load conditions. Using the same type of input on each device, the output is measured at V_{nnox}/2.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

Table 5C. AC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDOx} = 2.5V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency					250	MHz
	Propagation Delay,	CLK0; NOTE 1A		2.25	3.6	5.0	ns
tp _{LH}	Low to High	CLK1, nCLK1; NOTE 1B		3.1	3.8	4.4	ns
tsk(b)	Bank Skew; NOTE 2, 6					60	ps
tsk(o)	Output Skew; NOTE	3, 6				130	ps
tsk(pp)	Part-to-Part Skew; N	NOTE 4, 6				900	ps
t _R / t _F	Output Rise/Fall Tim	ne	20% to 80%	290		950	ps
odc	Output Duty Cycle		f ≤ 133MHz	45		55	%
t _{EN}	Output Enable Time; NOTE 5					10	ns
t _{DIS}	Output Disable Time	e; NOTE 5				10	ns

All parameters measured at 250MHz using CLK1, nCLK1 unless noted otherwise.

NOTE 1A: Measured from the $V_{DD}/2$ of the input to $V_{DDOX}/2$ of the output. NOTE 1B: Measured from the differential input crossing point to $V_{DDOX}/2$ of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at $V_{DDOX}/2$.

NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at V_DOOX/2.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

Table 5D. AC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDOx} = 1.8V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency					250	MHz
	Propagation Delay	CLK0; NOTE 1A		3.0	4.5	4.9	ns
tp _{LH} Propagation Delay, Low to High	CLK1, nCLK1; NOTE 1B		3.3	4.1	5.0	ns	
tsk(b)	Bank Skew; NOTE 2	2, 6				55	ps
tsk(o)	Output Skew; NOTE	3, 6				150	ps
tsk(pp)	Part-to-Part Skew; N	IOTE 4, 6				1.1	ns
t _R / t _F	Output Rise/Fall Tim	пе	20% to 80%	280		850	ps
odc	Output Duty Cycle		f ≤ 133MHz	45		55	%
t _{EN}	Output Enable Time; NOTE 5					10	ns
t _{DIS}	Output Disable Time	e; NOTE 5				10	ns

All parameters measured at 250MHz using CLK1, nCLK1 unless noted otherwise.

NOTE 1A: Measured from the $\rm V_{DD}\!/2$ of the input to $\rm V_{DDOX}\!/2$ of the output.

NOTE 1B: Measured from the differential input crossing point to $V_{\text{DDOX}}/2$ of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at $V_{DDOX}/2$.

NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with

equal load conditions. Using the same type of input on each device, the output is measured at V_{ppox}/2.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

Table 5E. AC Characteristics, $V_{DD} = 2.5V \pm 5\%$, $V_{DDOx} = 1.8V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency					250	MHz
	Propagation Delay,	CLK0; NOTE 1A		2.6	4.1	5.6	ns
tp _{LH}	Low to High	CLK1, nCLK1; NOTE 1B		3.3	4.4	5.4	ns
tsk(b)	Bank Skew; NOTE 2, 6					45	ps
tsk(o)	Output Skew; NOTE 3, 6					150	ps
tsk(pp)	Part-to-Part Skew; N	NOTE 4, 6				1.2	ns
t _R / t _F	Output Rise/Fall Tin	ne	20% to 80%	325		900	ps
odc	Output Duty Cycle		f ≤ 100MHz	45		55	%
t _{EN}	Output Enable Time; NOTE 5					10	ns
t _{DIS}	Output Disable Time	e; NOTE 5				10	ns

All parameters measured at 250MHz using CLK1, nCLK1 unless noted otherwise.

NOTE 1A: Measured from the $V_{\rm DD}/2$ of the input to $V_{\rm DDOX}/2$ of the output.

NOTE 1B: Measured from the differential input crossing point to $V_{\text{DDOX}}/2$ of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions.

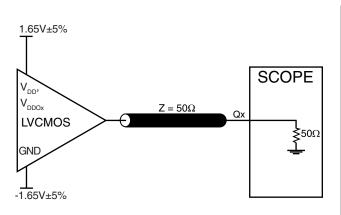
Measured at $V_{\text{DDOX}}/2$.

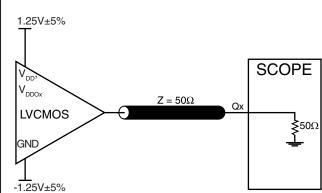
NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at $V_{DDOX}/2$.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

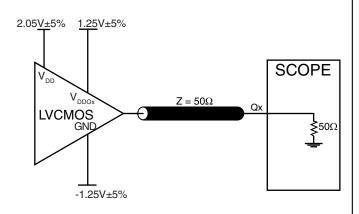
PARAMETER MEASUREMENT INFORMATION

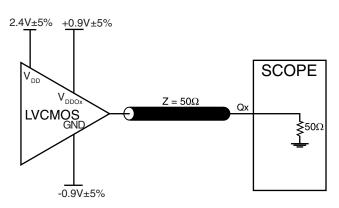




3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT

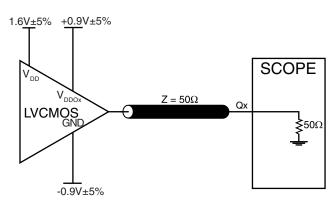
2.5V Core/2.5V OUTPUT LOAD AC TEST CIRCUIT

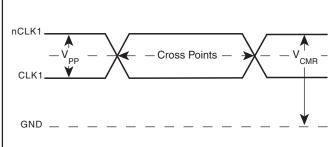




3.3V CORE/2.5V OUTPUT LOAD AC TEST CIRCUIT

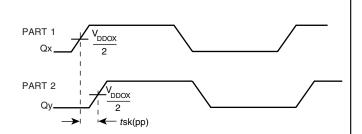
3.3V CORE/1.8V OUTPUT LOAD AC TEST CIRCUIT

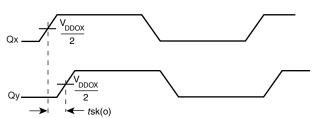




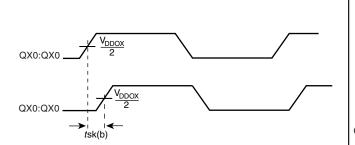
2.5V CORE/1.8V OUTPUT LOAD AC TEST CIRCUIT

DIFFERENTIAL INPUT LEVEL

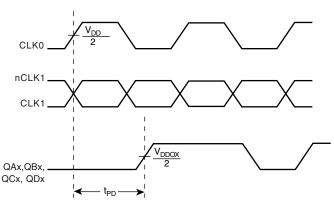




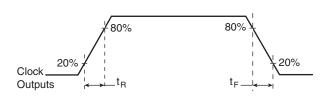
PART-TO-PART SKEW



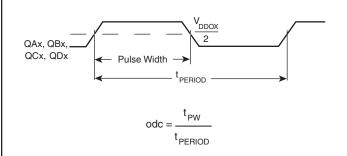
OUTPUT SKEW



BANK SKEW (where X denotes outputs in the same bank)



PROPAGATION DELAY



OUTPUT RISE/FALL TIME

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

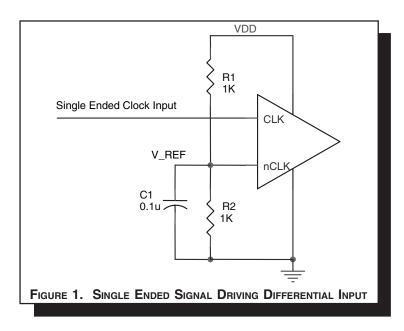


APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_REF = V_{DD}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{\rm DD}$ = 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.



DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. Figures 2A to 2E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested

here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 2A*, the input termination applies for ICS HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

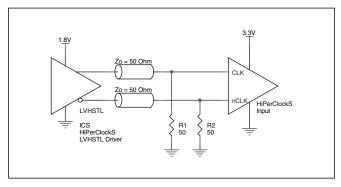


FIGURE 2A. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY ICS HIPERCLOCKS LVHSTL DRIVER

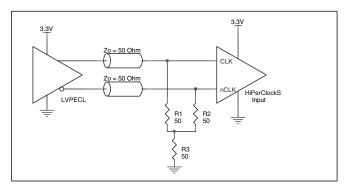


FIGURE 2B. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER



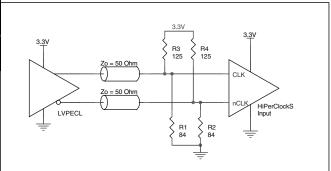


FIGURE 2C. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

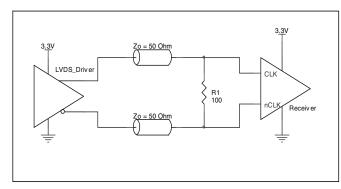


FIGURE 2D. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

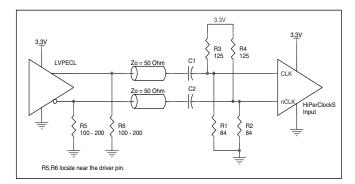


FIGURE 2E. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE

RELIABILITY INFORMATION

Table 6. $\theta_{\rm JA}{\rm vs.}$ Air Flow Table for 24 Lead TSSOP

 θ_{JA} by Velocity (Linear Feet per Minute)

200 0 500 Multi-Layer PCB, JEDEC Standard Test Boards 70°C/W 63°C/W 60°C/W

TRANSISTOR COUNT

The transistor count for ICS87008I is: 1262

PACKAGE OUTLINE - G SUFFIX FOR 24 LEAD TSSOP

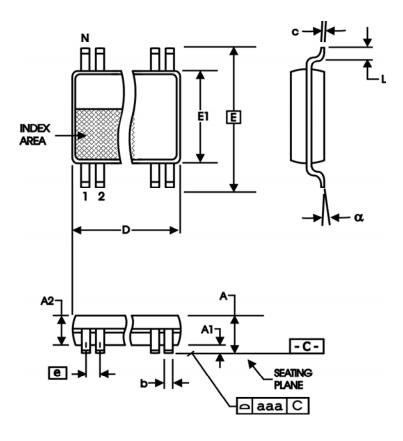


TABLE 7. PACKAGE DIMENSIONS

Millin	neters	
Minimum	Maximum	
24		
	1.20	
0.05	0.15	
0.80	1.05	
0.19	0.30	
0.09	0.20	
7.70	7.90	
6.40 [BASIC	
4.30	4.50	
0.65 E	BASIC	
0.45	0.75	
0°	8°	
	0.10	
	Minimum 2 0.05 0.80 0.19 0.09 7.70 6.40 E 4.30 0.65 E	

Reference Document: JEDEC Publication 95, MS-153

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TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS87008AGI	ICS87008AGI	24 Lead TSSOP	250 per tray	-40°C to 85°C
ICS87008AGIT	ICS87008AGI	24 Lead TSSOP on Tape and Reel	1000	-40°C to 85°C

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REVISION HISTORY SHEET						
Rev	Table	Page Description of Change		Date		
Α	T8	14	Ordering Information Table - added "T" (for tape and reel) Part/Order Number.	9/10/04		